

< L/S band internally matched power GaAs FET >

MGFL48V1920

1.9 - 2.0 GHz BAND / 60W

DESCRIPTION

The MGFL48V1920 is a 60W push-pull type GaAs power FET especially designed for use in 1.9 - 2.0 GHz band amplifiers. The hermetically sealed metal-ceramic package guarantees high reliability.

FEATURES

Push-pull configuration

- High output power Pout=60W (TYP.) @f=1.9 - 2.0GHz
- High power gain GLP=11.5dB (TYP.) @f=1.9 - 2.0GHz
- High power added efficiency
 P.A.E.=45% (TYP.) @f=1.9 2.0GHz

APPLICATION

• item 01: 1.9 - 2.0 GHz band power amplifier

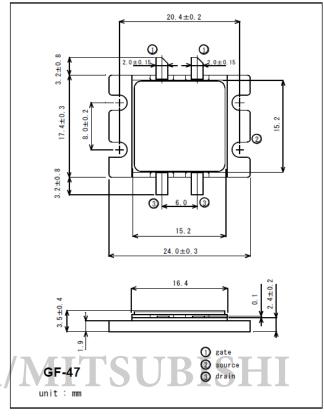
QUALITY

• IG

RECOMMENDED BIAS CONDITIONS

• VDS=12V • ID=4.0A • RG=20ohm for each gate





Absolute maximum ratings (Ta=25°C)

Symbol	Parameter Ratings		Unit
VGDO	Gate to drain breakdown voltage	-20	V
VGSO	Gate to source breakdown voltage	e to source breakdown voltage -10	
PT *1	Total power dissipation	10	W
Tch	Cannel temperature	175	°C
Tstg	Storage temperature	-65 to +175	°C

*1 : Tc=25°C

Keep Safety first in your circuit designs! Mitsubishi Electric Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage. Remember to give due consideration to safety when making your circuit designs, with appropriate measure such as (I) placement of substitutive, auxiliary circuits, (ii) use of non-flammable material or (iii) prevention against any malfunction or mishap.

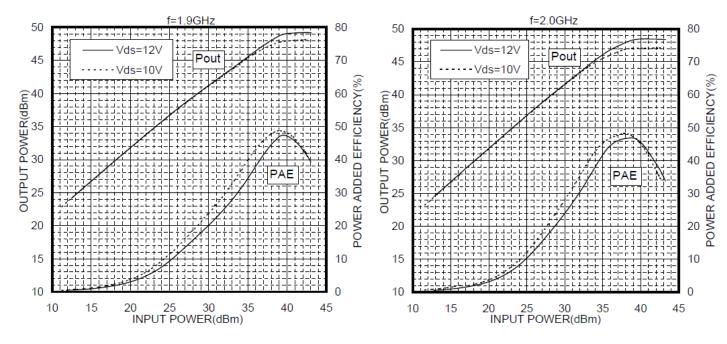
Electrical characteristics (Ta=25°C)

Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Тур.	Max.	
VGS(off)	Gate to source cut-off voltage	VDS=3V,ID=17.3mA	-1	-	-4	V
P2dB	Output power at 2dB gain compression	VDS=12V,ID(RF off)=4.0A	47	48	-	dBm
GLP	Linear Power Gain	f=1.9 - 2.0GHz	10	11.5	-	dB
ID	Drain current]	-	11	15	Α
P.A.E.	Power added efficiency]	-	45	-	%
Rth(ch-c) *2	Thermal resistance	delta Vf method	-	1.0	1.4	°C/W

^{*2 :}Channel-case

MGFL45V1920 TYPICAL CHARACTERISTICS

Pout, PAE vs. Pin



Test Condition: Idq=4A,Ta=25deg.C

IMD vs. Pout

-24

-26

-28

-30

-32

-34

-36

-38

-42

-44

-46

-48

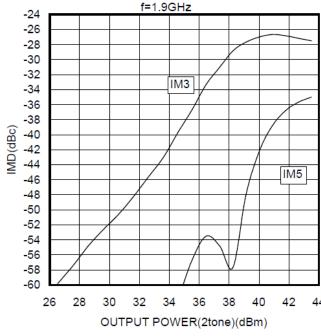
-50

-52

-54

-56

IMD(dBc) -40



-58 -60 44 26 28 30 32 34 OUTPUT POWER(2tone)(dBm) Test Condition: Vds=12V,Idq=4A,Ta=25deg.C

Publication Date: Apr., 2011

2-tone test , $\Delta f=5MHz$

36

38

40

42

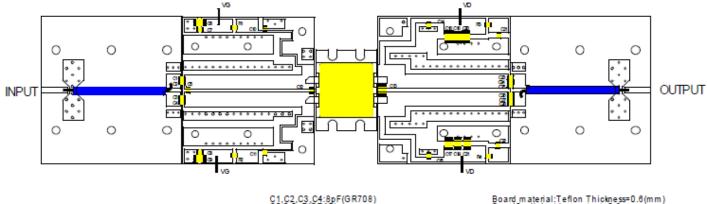
44

f=2.0GHz

IM3

IM5

MGFL45V1920 RF TEST FIXTURE

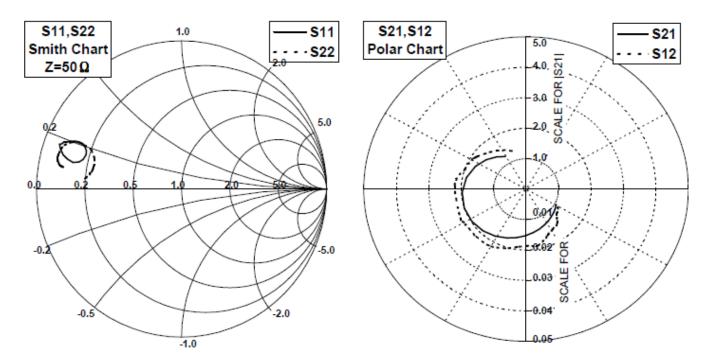


C1.C2.C3.C4:8pF(GR708) C5:0.5pF(GR40) C7.C8:4700pF(GR40) C6.C9.C18.C17.C18.C19.C20.C21:4.7uF(CM32) C10.C11.C14.C15:20pF(GR40) C12:1.5pF(GR40) C12:1.C22:1000pF(GR40) C21.C22:1000pF(GR40) C23.C24.C25.C26.C27.C28:13pF(GR708) R1.R2=20ohm R3.R4=51ohm

Board material:Teflon Thickness=0.6(mm) Specific dielectric constant=2.6

www.BDTIC.com/MITSUBISHI

MGFL48V1920 S-parameters (Ta=25deg.C, VDS=12(V),IDS=1.5(A))



www.BDTIC.com/MITSUBISHI

	S Parameters (TYP.)								
f	S11		S	S21 S [*]		12 S:		522	
(GHz)	Mag.	Ang(deg.)	Mag.	Ang(deg.)	Mag.	Ang(deg.)	Mag.	Ang(deg.)	
1.50	0.889	160.2	1.056	-28.4	0.012	-31.0	0.830	169.7	
1.55	0.879	159.5	1.101	-35.3	0.012	-38.3	0.837	169.6	
1.60	0.869	158.7	1.147	-42.4	0.013	-40.8	0.840	169.5	
1.65	0.854	158.2	1.197	-49.6	0.014	-48.0	0.846	169.4	
1.70	0.843	157.6	1.253	-57.1	0.015	-50.4	0.854	169.2	
1.75	0.829	157.2	1.310	-64.9	0.016	-65.6	0.862	168.6	
1.80	0.814	156.6	1.379	-73.0	0.017	-67.8	0.870	167.7	
1.85	0.800	156.3	1.451	-81.6	0.019	-79.1	0.878	166.8	
1.90	0.782	155.8	1.529	-90.6	0.019	-88.1	0.881	165.3	
1.95	0.761	155.9	1.617	-100.0	0.019	-98.3	0.877	163.8	
2.00	0.741	156.1	1.710	-110.3	0.020	-108.0	0.873	161.9	
2.05	0.722	157.0	1.813	-121.5	0.022	-121.7	0.858	159.8	
2.10	0.705	158.5	1.909	-133.8	0.022	-136.4	0.827	157.7	
2.15	0.697	160.7	1.977	-147.2	0.022	-150.5	0.782	156.1	
2.20	0.707	163.6	2.005	-161.9	0.022	-153.5	0.732	156.0	
2.25	0.730	165.5	1.971	-176.8	0.022	176.6	0.673	157.4	
2.30	0.769	166.6	1.873	168.3	0.020	161.0	0.635	161.2	
2.35	0.811	165.6	1.725	154.3	0.019	148.0	0.624	166.0	
2.40	0.847	164.3	1.560	141.6	0.016	132.7	0.635	170.3	
2.45	0.875	162.3	1.395	130.6	0.015	118.7	0.661	173.3	
2.50	0.895	160.1	1.246	120.8	0.013	105.3	0.687	175.2	

This S-Parameter data show measurements performed on each single-ended FET.

Keep safety first in your circuit designs!

Mitsubishi Electric Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage. Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of non-flammable material or (iii) prevention against any malfunction or mishap.

Notes regarding these materials

- •These materials are intended as a reference to assist our customers in the selection of the Mitsubishi semiconductor product best suited to the customer's application; they do not convey any license under any intellectual property rights, or any other rights, belonging to Mitsubishi Electric Corporation or a third party.
- •Mitsubishi Electric Corporation assumes no responsibility for any damage, or infringement of any third-party's rights, originating in the use of any product data, diagrams, charts, programs, algorithms, or circuit application examples contained in these materials.
- •All information contained in these materials, including product data, diagrams, charts, programs and algorithms represents information on products at the time of publication of these materials, and are subject to change by Mitsubishi Electric Corporation without notice due to product improvements or other reasons. It is therefore recommended that customers contact Mitsubishi Electric Corporation or an authorized Mitsubishi Semiconductor product distributor for the latest product information before purchasing a product listed herein.
- The information described here may contain technical inaccuracies or typographical errors. Mitsubishi Electric Corporation assumes no responsibility for any damage, liability, or other loss rising from these inaccuracies or errors.
- Please also pay attention to information published by Mitsubishi Electric Corporation by various means, including the Mitsubishi Semiconductor home page (http://www.MitsubishiElectric.com/).
- •When using any or all of the information contained in these materials, including product data, diagrams, charts, programs, and algorithms, please be sure to evaluate all information as a total system before making a final decision on the applicability of the information and products. Mitsubishi Electric Corporation assumes no responsibility for any damage, liability or other loss resulting from the information contained herein.
- •Mitsubishi Electric Corporation semiconductors are not designed or manufactured for use in a device or system that is used under circumstances in which human life is potentially at stake. Please contact Mitsubishi Electric Corporation or an authorized Mitsubishi Semiconductor product distributor when considering the use of a product contained herein for any specific purposes, such as apparatus or systems for transportation, vehicular, medical, aerospace, nuclear, or undersea repeater use.
- •The prior written approval of Mitsubishi Electric Corporation is necessary to reprint or reproduce in whole or in part these materials.
- •If these products or technologies are subject to the Japanese export control restrictions, they must be exported under a license from the Japanese government and cannot be imported into a country other than the approved destination.
- Any diversion or re-export contrary to the export control laws and regulations of Japan and/or the country of destination is prohibited.
- •Please contact Mitsubishi Electric Corporation or an authorized Mitsubishi Semiconductor product distributor for further details on these materials or the products contained therein.